

IPU 18

PATENT APPLICATION  
10551/489

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: J. Thomas WALKER

Application No.: 10/625,552

Examiner: DINH, TUAN T

Group Art Unit: 2841

Confirmation No. 8103

Filed: July 24, 2003

For: ATTACHABLE MODULAR ELECTRONIC SYSTEMS

INFORMATION DISCLOSURE STATEMENT

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

03/11/2005 SDENR0B1 00000142 110600 10625552

01 FC:1806

180.00 DA

Sir:

Pursuant to 37 CFR § 1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom. The filing of this Information Disclosure Statement and the enclosed PTO Form No. 1449, shall not be construed as an admission that the information cited is prior art, or is considered to be material to patentability as defined in 37 C.F.R. § 1.56(b). The paragraphs marked below are applicable. It is believed that no fees other than those indicated below are due, but authorization is hereby given to charge any additional fees due, or to credit any overpayment, to deposit account 11-0600.

■ 1. This Information Disclosure Statement is being filed (a) within three months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. § 1.53(d), (b) within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, (c) before the mailing date of a first Office Action on the merits in the present application, OR (d) before the mailing of a first office action after filing of a request for continued examination. No certification or fee is required.

2. This Information Disclosure Statement is being filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a final action, Notice of Allowance, or any action that otherwise closes prosecution.

BEST AVAILABLE COPY

Applicant: J. Thomas WALKER  
Serial No. 10/625,552  
IDS filed March 10, 2005

a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

b. I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).

c. Please debit Deposit Account No. 11-0600 in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p) to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached. 37 CFR §1.97(c)(2).

3. This Information Disclosure Statement is being filed after the mailing date of a final action, Notice of Allowance or an action that otherwise closes prosecution, but before payment of the Issue Fee. Applicant(s) hereby request(s) that the Information Disclosure Statement be considered. Please debit Deposit Account No. 11-0600 in the amount of \$180.00 in payment of the petition fee under 37 CFR §1.17(p) to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached.

a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in any counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

b. I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).


Respectfully submitted,

KENYON & KENYON

Date:

March 10, 2005

Suite 700  
1500 K Street, N.W.  
Washington, D.C. 20005  
Telephone: (202) 220-4200  
Facsimile: (202) 220-4201

  
Kenneth R. Corsello  
Registration No. 38,115

BEST AVAILABLE COPY

MAR 10 2005

PTO/SB/08a (08-03)

Approved for use through 07/31/2006. OMB 0651-0031

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Sheet 1 of 3

**Complete if Known**

Application Number	10/625,552
Filing Date	July 24, 2003
First Named Inventor	J. Thomas WALKER
Art Unit	2841
Examiner Name	DINH, TUAN T
Attorney Docket Number	10551/489

**U.S. PATENT DOCUMENTS**

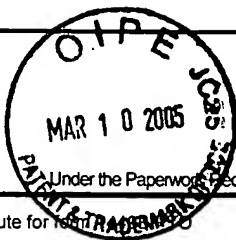
Examiner Initials *	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code <sup>2</sup> (if known)			
		US-6,297,564 B1	10-02-2001	Chung	
		US- 6,297,559 B1	10-02-2001	Call et al.	
		US- 6,184,053 B1	02-06-2001	Eldridge et al.	
		US- 5,818,107	10-06-1998	Pierson et al.	
		US- 5,365,656	11-22-1994	Dahringer et al.	
		US- 4,848,650	07-18-1989	Gieskes	
		US- 4,701,279	10-20-1987	Kawaguchi et al.	

**FOREIGN PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> - Number <sup>4</sup> - Kind Code <sup>5</sup> (if known)				
		EP 0 948 813 B1	10-09-1997	Hans-Hermann Oppermann et al.		
		EP 0 933 010 B1	08-15-1997	Hugh P. Craig		
		EP 0 753 827 B1	07-04-1996	Francois Launay et al.		
		EP 0 711 103 B1	11-02-1994	Donald William Dahringer et al.		
		EP 0 455 455 B1	04-29-1991	Fabriel Lorimer Miller		
		EP 0 292 079 B1	05-19-1988	Koenraad Alexander Gieskes		
		EP 0 147 856 B1	12-27-1984	Yoshio Fujiwara et al.		
		EP 1 114 852 B1	07-11- 2001	Hiroaki Takezawa et al.		
		EP 1 108 766 A2	06-20-2001	Polymatech Co., Ltd.		
		WO 97/43654	11-20-1997	Igor Y. Khandros		
		JP 09-303101	10-13-1998	Interuniv Micro Electron Centrum VZW		
		JP 62-286984	05-22-1989	L EE C:KK		
		JP 09-189506	04-28-2000	Murata Mfg Co Ltd		
		JP 11-40927	02-12-1999	Mitsubishi Heavy Ind Ltd		
		JP 63-220512	08-03-1990	Toshiba Corp		
		JP 03-246773	12/03/1993	Techno Sunstar		

Examiner  
SignatureDate  
Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached. This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



PTO/SB/08b(08-03)

Approved for use through 07/31/2006. OMB 0651-0031

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

Substitute for form PTO/SB/08b(08-03)

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Sheet

2

Of

3

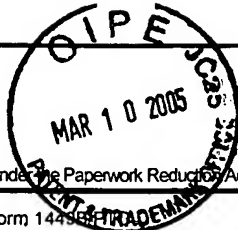
**Complete if Known**

Application Number	10/625,552
Filing Date	July 24, 2003
First Named Inventor	J. Thomas WALKER
Art Unit	2841
Examiner Name	DINH, TUAN T
Attorney Docket Number	10551/489

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		"Theoretical and Experimental Aspects in the Depositing Process of Solder and Adhesive Pates in Surface Mount Technology," Alexandru Marin et al., IEEE Polytronic 2002 Conference, pp. 150-154.	
		"Isotropically Conductive Adhesives for High Power Electronics Applications," Kristian Olsson et al., IEEE Polytronic 2002 Conference, pp. 29-37.	
		"Conductive Adhesive Fillets for Double Sided PCBs," Ryszard Kisiel, et al., IEEE Polytronic 2002 Conference, pp. 13-16.	
		"The Influence of Filler Particle Shapes on Adhesive Joints in Microwave Applications," Jan Felba, et al., IEEE Polytronic 2002 Conference, pp. 1-6.	
		"Development of Fine Pitch (54µm) Flip Chip on Flex Interconnection Process," Jarmo Määttänen et al., IEEE Polytronic 2002 Conference, pp. 155-159.	
		"Microwave Cure of Conductive Adhesives for Flip-Chip & Microsystems Applications," G.P. Glinski et al., 2002 InterSociety Conference on Thermal Phenomena, pp. 848-853.	
		"Flip Chip Joining of Thin Chips on Flexible PEN Substrate," Erja Jokinen et al., 2001 International Symposium on Microelectronics, pp. 600-604.	
		"The Development and Reliability of Small Pitch Flip Chip on Flex Process," Petteri Palm et al., 2001 International Symposium on Electronic Materials and Packaging, pp. 428-432.	
		"A Study on Advanced Flip Chip Interconnect Technologies for Space Application," Sharon Ling et al., 2001 International Conference on High-Density Interconnect and Systems Packaging, pp. 131-136.	
		"Polymeric Materials for Adaptronic Fibre Modules," Helmut Schaefer et al., Session 4: Polymer Electronic Devices II, pp. 98-103.	
		"Electrical Conduction of Adhesive Joints in Microwave Application," Jan Felba et al., Session 3, Isotropic Conductive Adhesives, 2001, IEEE, pp. 71-78.	
		"PC 3000 - The New Generation of Isotropic Conductive Adhesives," by Jens Neumann-Rodekirch et al., Session 3: Istropic Conductive Adhesives, 2001 IEEE, p. 70.	
		"Electroconductive Adhesives to Grow into Major Market," <u>Japan Chemical Week</u> , January 16, 2003, p. 3.	
		"U.S. Demand for Electronic Polymer Products to Expand 6.4% Annually Through 2005," Adhesives & Sealants Industry, Vol. 9, Number 4, May 2002, p. 26.	

Examiner  
SignatureDate  
Considered



PTO/SB/08b(08-03)

Approved for use through 07/31/2006. OMB 0651-0031  
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

Substitute for form 1449

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Sheet 3 Of 3

**Complete if Known**

Application Number	10/625,552
Filing Date	July 24, 2003
First Named Inventor	J. Thomas WALKER
Art Unit	2841
Examiner Name	DINH, TUAN T
Attorney Docket Number	10551/489

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		"Lead-Free Pastes Fail to Stick," <u>Adhesives Age</u> , Vol. 44, No. 9, September 2001, p. 9.	
		"Using Conductive Adhesives for Grounding Applications," Stanley Tead et al., 23rd-24th October 2000, Paper 115, Conference Paper, Charlotte, NC.	
		"More Secure Bonding for Fine Pitch Surface Mount Device Structural Elements," (English translation), by Thomas Gesang et al., Adhasion Kleben & Dichten, pp. 27-32, Nos. 7-8, 1998.	
		"Niche Applications Lift the Adhesives and Sealants Market," <u>Chemical Market Reporter</u> , May 21, 2001, Vol. 259, No. 21.	
		Jarmo Määttänen et al., "Development of Fine Pitch (54 µm) Flip Chip on Flex Interconnection Process," <i>IEEE Polytronic 2002 Conference</i> , pp. 155-159, 2002.	
		Rainer Möst, "Electronic Adhesives New Solutions for Short Cycled Manufacturing Process," <i>First International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics</i> , pp. 242-249, October 21-24, 2001.	
		Carl Yallop, "Conductive adhesives provide solution to electronic assembly problems," <i>European Design Engineer</i> , October 2001, pp. 50-51.	

Examiner  
SignatureDate  
Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered.